

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (original): A wiring board comprising:  
  
a conductor layer comprising Fe and Cu; and  
  
at least one of a radiator, a connection terminal, a cover and a circuit component,  
  
connected to the conductor layer through a joining member.
2. (original): The wiring board according to claim 1, wherein a surface of the conductor layer is subjected to a plating treatment.
3. (original): The wiring board according to claim 1, which is obtained by coating a copper paste comprising a copper powder, an organic vehicle and an Fe<sub>2</sub>O<sub>3</sub> particle as a conductor layer on a ceramic green sheet and firing it.
4. (original): The wiring board according to claim 3, wherein the copper paste comprises more than 20 parts by mass of the organic vehicle per 100 parts by mass of the copper powder.
5. (original): The wiring board according to claim 3, wherein the copper paste comprises a ceramic particle having an average particle size of 100 nm or less.
6. (original): The wiring board according to claim 3, which is obtained by a method comprising the steps of  
  
coating the copper paste on a ceramic green sheet;

exposing the coated sheet to a wet nitrogen atmosphere at 650 to 900°C so as to remove organic components; and

firing the sheet at 850 to 1,050°C after the exposing.

7. (original): A copper paste comprising a copper powder, an organic vehicle and an  $\text{Fe}_2\text{O}_3$  particle.

8. (original): The copper paste according to claim 7, wherein the copper paste comprises more than 20 parts by mass of the organic vehicle per 100 parts by mass of the copper powder.

9. (original): The copper paste according to claim 7, which comprises a ceramic particle having an average particle size of 100 nm or less.